APPLICATION NOTE

Waffle Pack Chip Carrier Handling/Opening Procedure

Proper ESD handling practice should be adhered to at all times when handling Skyworks product.

Step 1
Remove carrier clip. Do not allow separation between the waffle pack and cover.

Step 2
Place lidded waffle pack onto a flat ESD surface. Avoid separation between the waffle pack and cover.

Step 3
Gently tap cover using the handle of a set of tweezers. This will remove any devices that are clinging to the inside paper.

Step 4
Lift cover.

Step 5
Remove the two layers of paper. They should be slid off the waffle pack with light pressure.

Step 6
Remove die from carrier. The use of a vacuum tool is strongly suggested. Tweezers should not be used to remove die.

Caution: Devices should only be handled at an ESD approved workstation.

Waffle pack chip carriers are made of ChipSentry® black conductive polycarbonate from fluoroware.
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ESD Awareness
Skyworks deploys state of the art ESD controls from wafer fabrication through to assembly, test and pack. In order to maintain device integrity, Skyworks has outlined critical ESD guidelines that should be followed as a minimum. Skyworks adheres to the requirements outlined in MIL-HDBK-263, MIL-STD-1686 and ESD Association 2.0 Handbook.

Device Handling
Remove ESD sensitive devices from protective containers at approved ESD work stations only.
ESD wrist straps are required when handling devices outside their ESD protective packaging.
All personnel shall be properly grounded (footstraps/wrist straps) prior to opening static shielding bags.
ESD sensitive devices should always be handled by the part body. Avoid touching the leads. When hand tools are required to accomplish an operation, use only dissipative, conductive, or tools treated with topical antistat.

Closing

Step 1
When closing the package the two layers of paper should be aligned properly with the waffle pack.

Step 2
The cut corner in the upper left should match up on the waffle pack and cover. The clip can be put back on when the cover is properly set on waffle pack.

Step 3
Slide carrier clip on. Avoid separation between the waffle pack and cover.

ESD Workstation
Your ESD safe work area should follow the requirements outlined in MIL-HDBK-263 and ESD Association Handbook 2.0. The following requirements are strongly recommended:

Personnel
The use of constant wrist strap monitors is highly recommended. This monitor guarantees that the connection to ground is continuously made. An alarm will sound when that connection is broken.

Clothing
An ESD protective garment (smock, etc.) shall be used at the workstation. While a person may be grounded using a wrist strap or foot strap, that does not ensure that certain clothing fabrics can dissipate a charge to ground. The use of a conductive smock is required.

Floors
Conductive or dissipative ESD flooring should be utilized whenever possible. This flooring shall be checked for ESD properties on a regular basis.

Work Surfaces
Your ESD work surface should be covered with soft dissipative material. This surface shall be tied to earth ground and shall be configured in a common point ground. In addition, the work surface shall be free of any static generating material, such as non-essential plastics, or scotch tape.

Equipment
All equipment used to process ESD sensitive devices shall be checked for the generation of static charging. Whether soldering irons, wave solder machines, device insertion machines or test equipment, the generation of static electricity is of concern.